

BCC Products HPX-850 Epoxy Backfill System

Category : Polymer , Thermoset , Epoxy

Material Notes:

HPX-850 is a light weight, heat resistant, two component epoxy backfill system. HPX-850 features advantages such as low cost, long pot life, machineability, and low shrinkage. HPX-850 is ideally suited for numerous applications involving mold and core construction. Information provided by BCC Products, Inc.

Order this product through the following link:

http://www.lookpolymers.com/polymer_BCC-Products-HPX-850-Epoxy-Backfill-System.php

Physical Properties	Metric	English	Comments
Specific Gravity	0.820 g/cc	0.820 g/cc	
Linear Mold Shrinkage	0.00020 cm/cm	0.00020 in/in	ASTM D2566-69

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	74	74	
	@Temperature 23.9 °C	@Temperature 75.0 °F	
Compressive Strength	34.3 MPa	4980 psi	

Thermal Properties	Metric	English	Comments
Deflection Temperature at 1.8 MPa (264 psi)	141 °C	285 °F	

Processing Properties	Metric	English	Comments
Cure Time	1440 min	24.0 hour	
	@Temperature 24.0 °C	@Temperature 75.2 °F	
Pot Life	120 - 150 min	120 - 150 min	1/2 lb. mass
	@Temperature 24.0 °C	@Temperature 75.2 °F	

Descriptive Properties	Value	Comments
Mix Ratio	6:1 by weight, resin/hardener	
Mixed Viscosity, Brookfield	Thixotropic	

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